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(12) **United States Design Patent**  
**Mertler**

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(54) **GROUND FAULT CIRCUIT INTERRUPTER  
(GFCI) PRINTED CIRCUIT BOARD  
PACKAGE**

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(\*\*) Term: **14 Years**

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(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/133, 145, 182; 174/68.1, 250, 253,  
174/255, 256; 318/567, 568.1; 361/600,  
361/601, 719, 720, 728, 736, 748, 751, 752,  
361/760, 761, 807; 439/55, 65, 68, 69, 70,  
439/76.1, 92, 93, 95, 98, 100, 101, 108;  
702/57, 58, 59

See application file for complete search history.

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*Primary Examiner* — Elizabeth J Oswecki

(57) **CLAIM**

The ornamental design for a ground fault circuit interrupter (GFCI) printed circuit board package, as shown and described.

**DESCRIPTION**

FIG. 1 is a top perspective view of a ground fault circuit interrupter (GFCI) printed circuit board package showing our new design;

FIG. 2 is a rear elevation view thereof;

FIG. 3 is a front elevation view thereof;

FIG. 4 is a top plan view thereof;

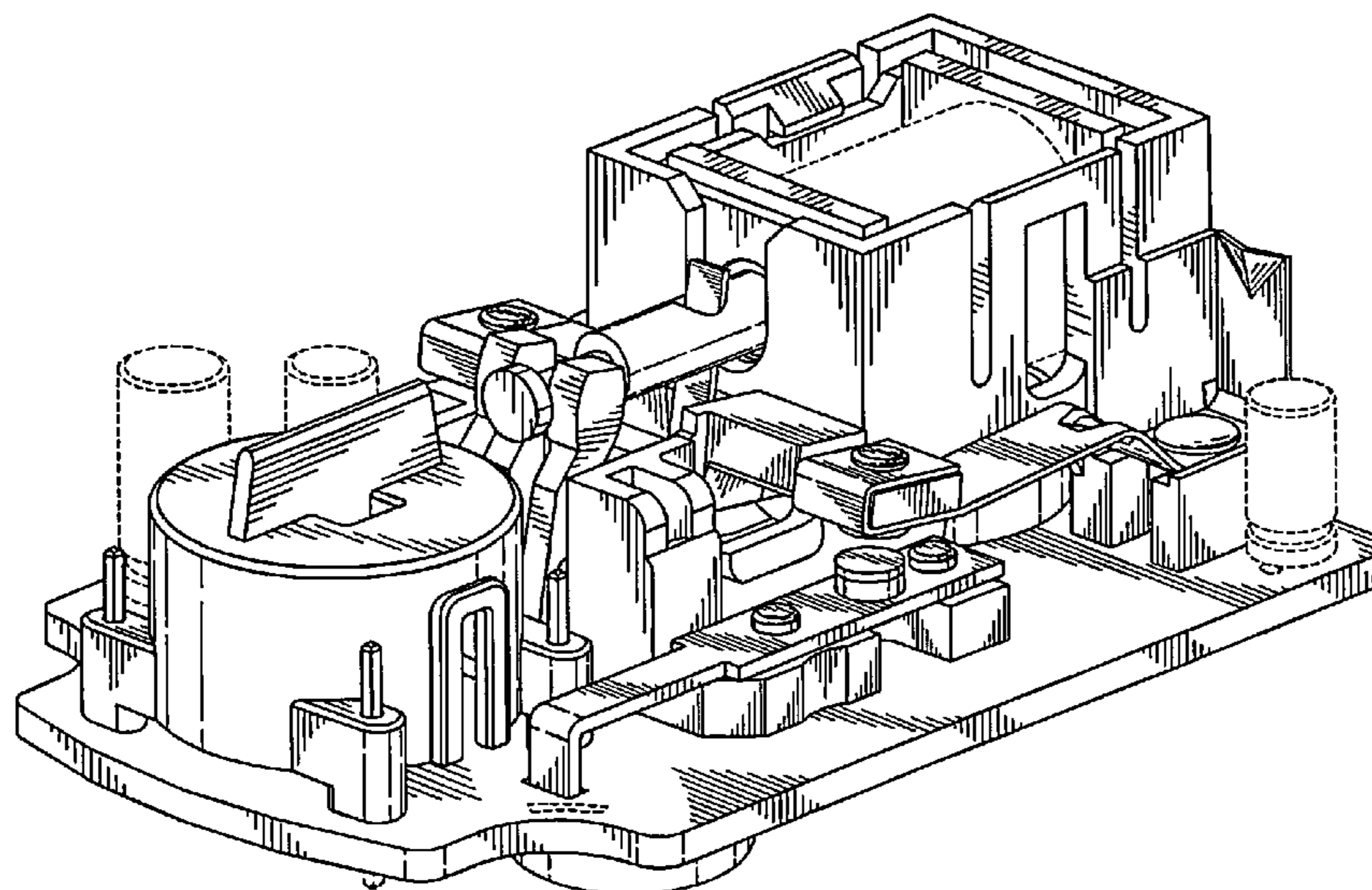
FIG. 5 is a bottom plan view thereof;

FIG. 6 is a left side view thereof; and,

FIG. 7 is a right side view thereof.

The broken lines shown in the drawings of FIGS. 1-7 represent portions of the ground fault circuit interrupter (GFCI) printed circuit board package that form no part of the claimed design.

**1 Claim, 7 Drawing Sheets**



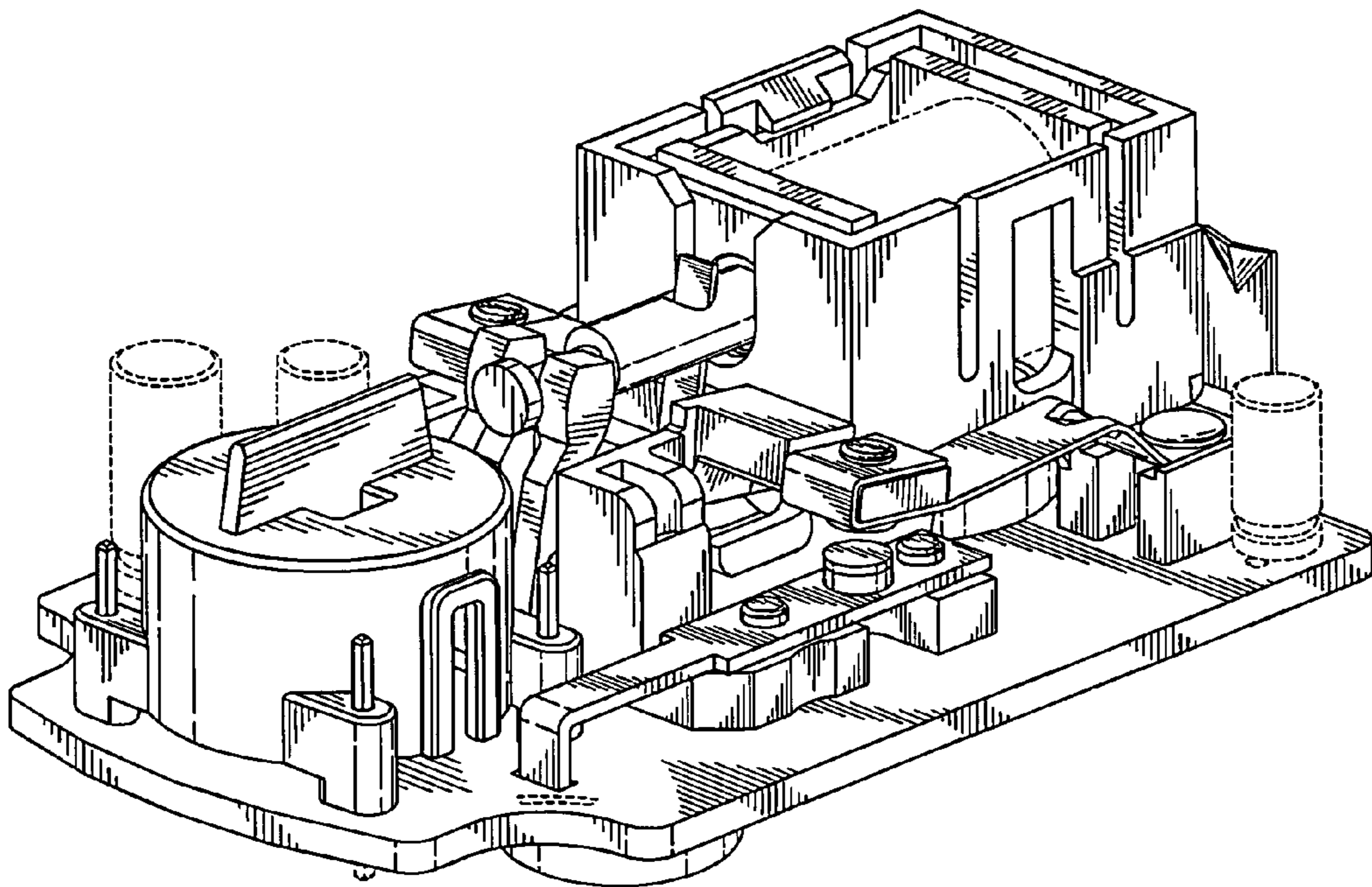


FIG. 1

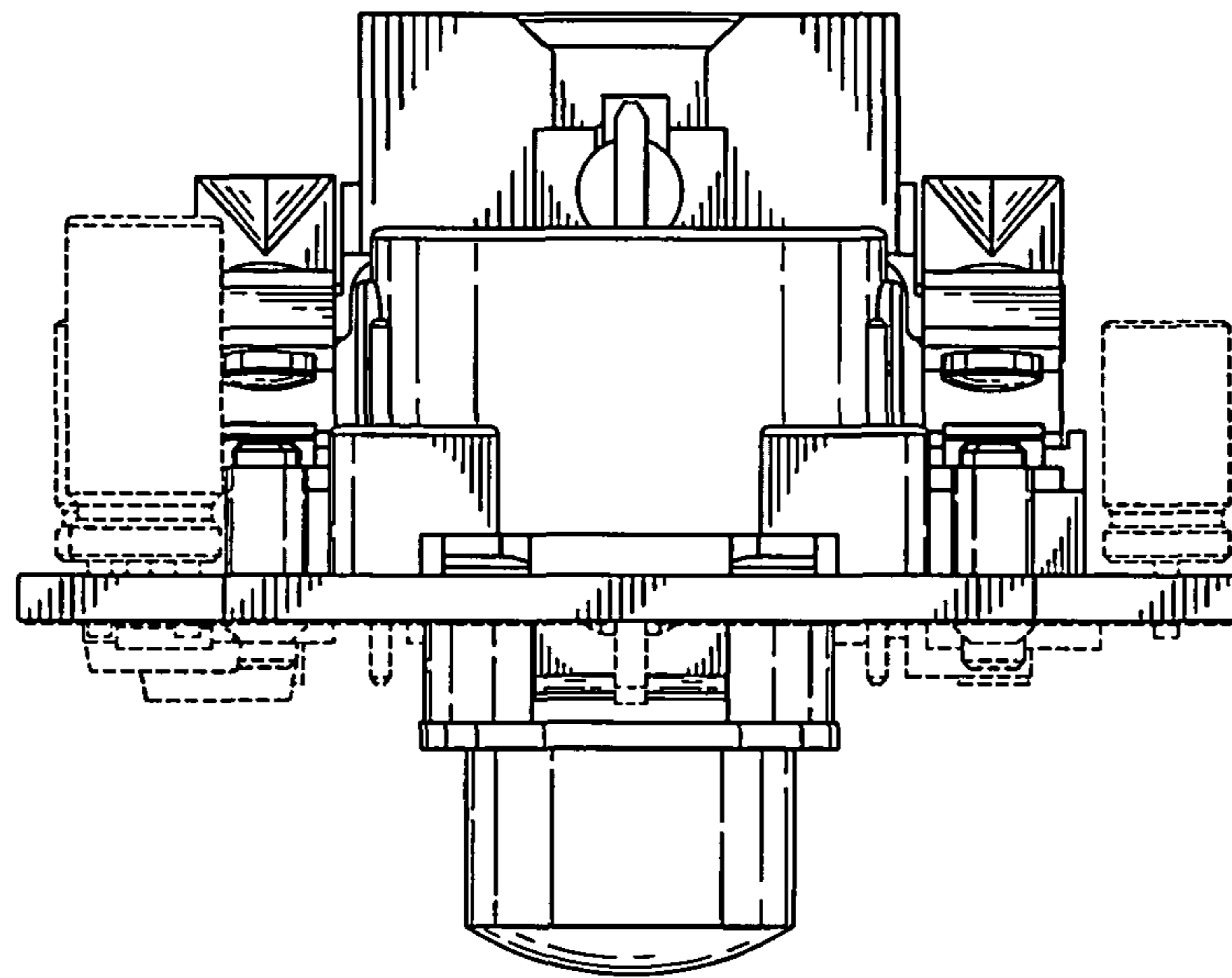


FIG. 2

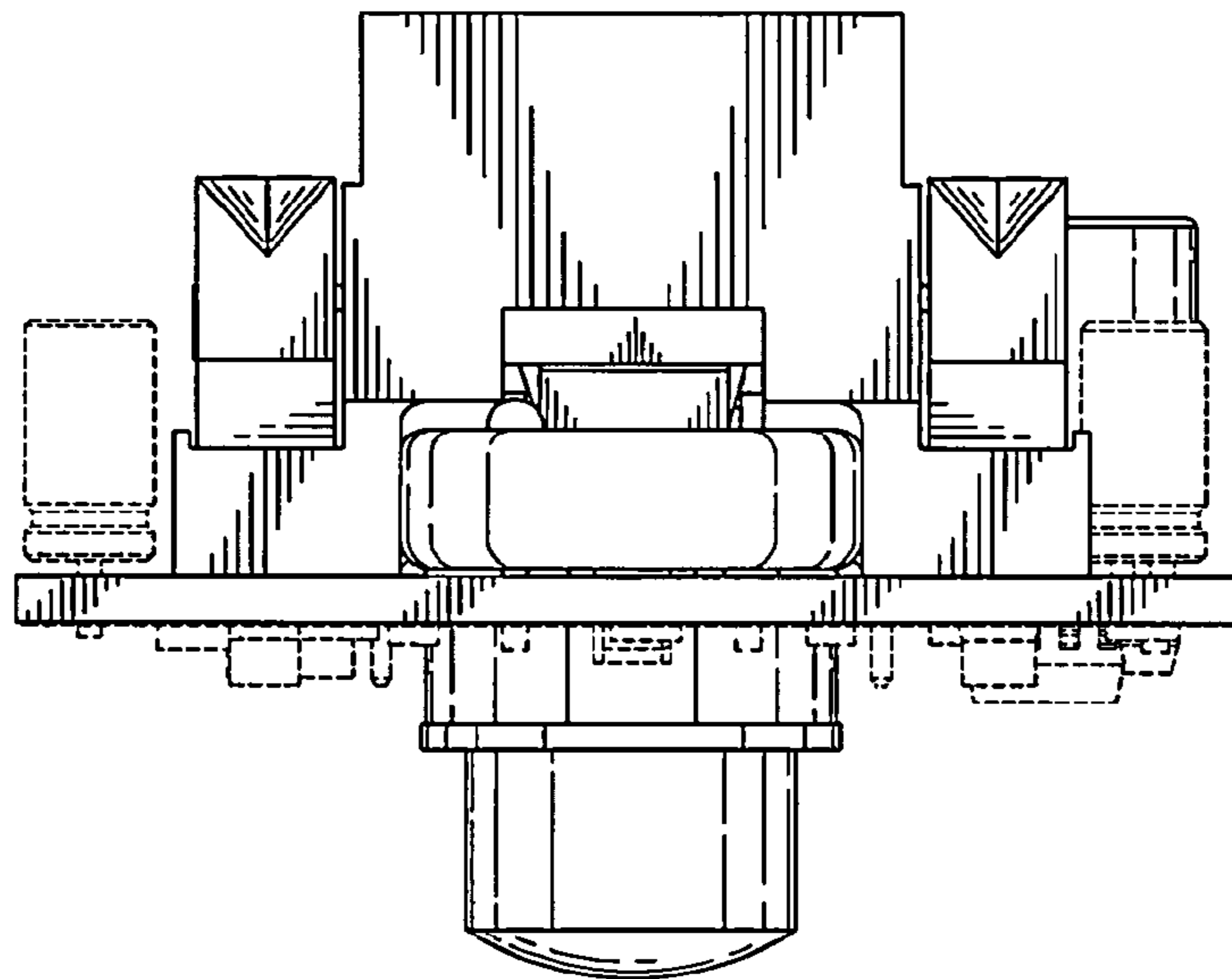


FIG. 3

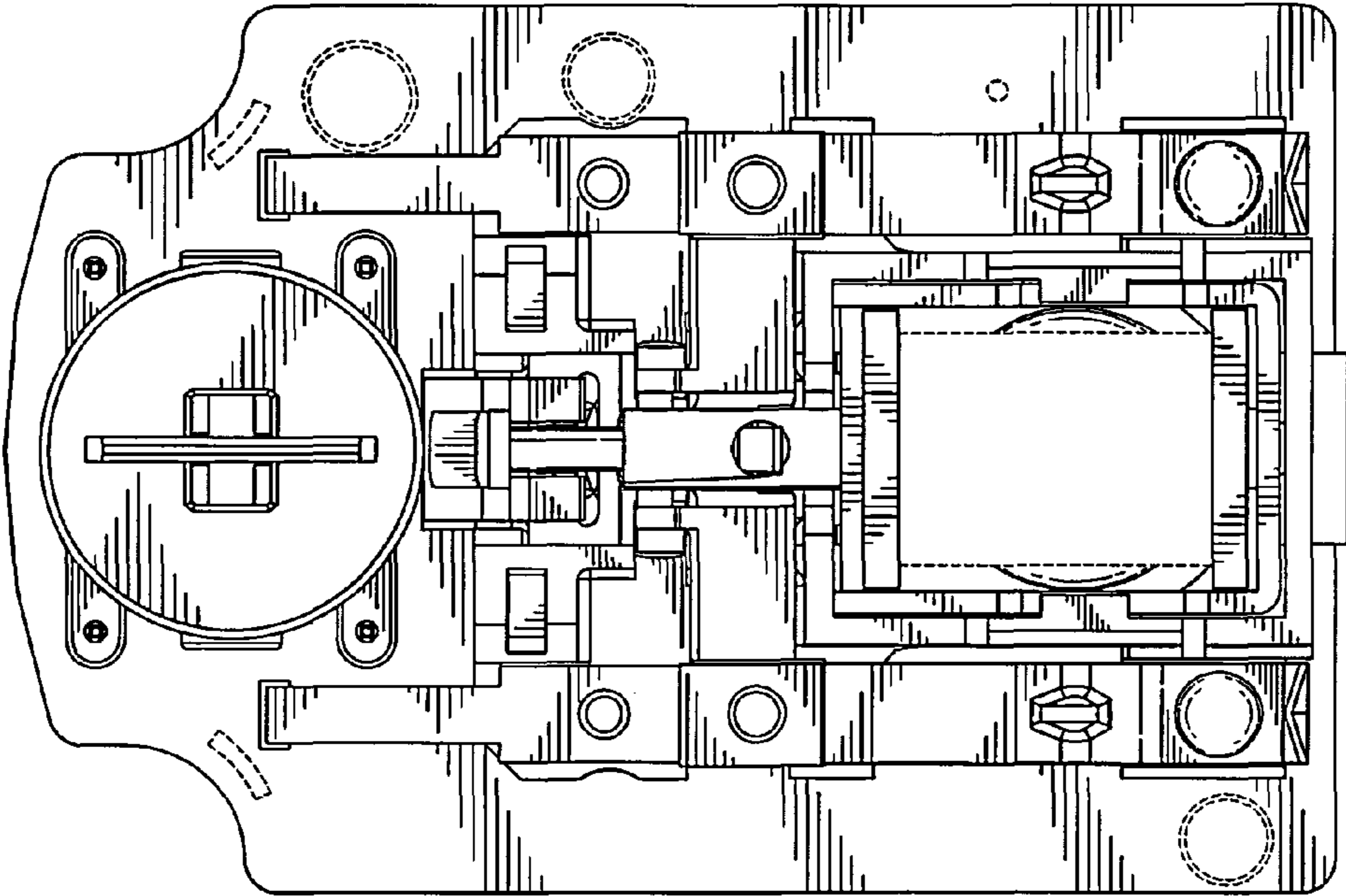


FIG. 4

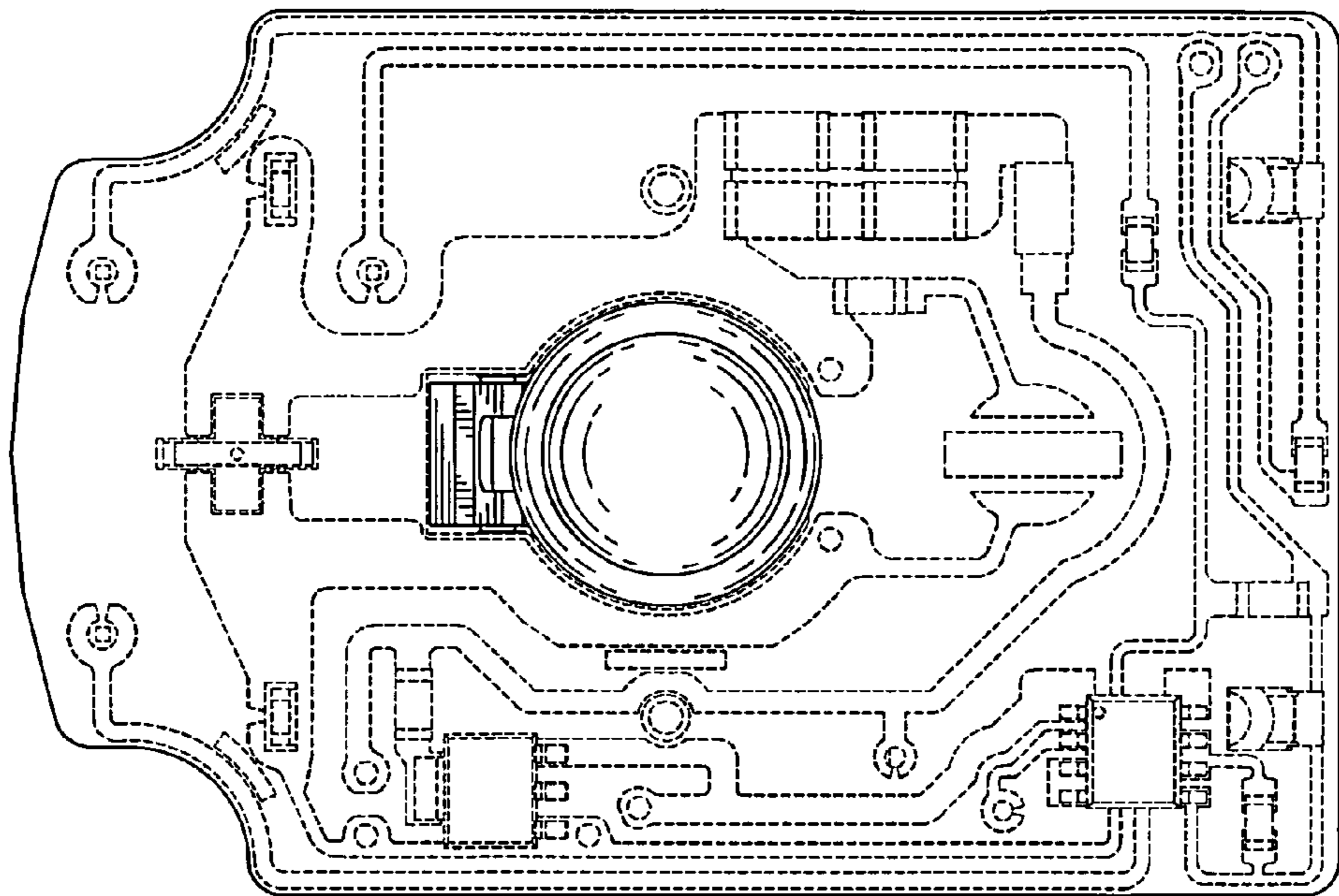


FIG. 5

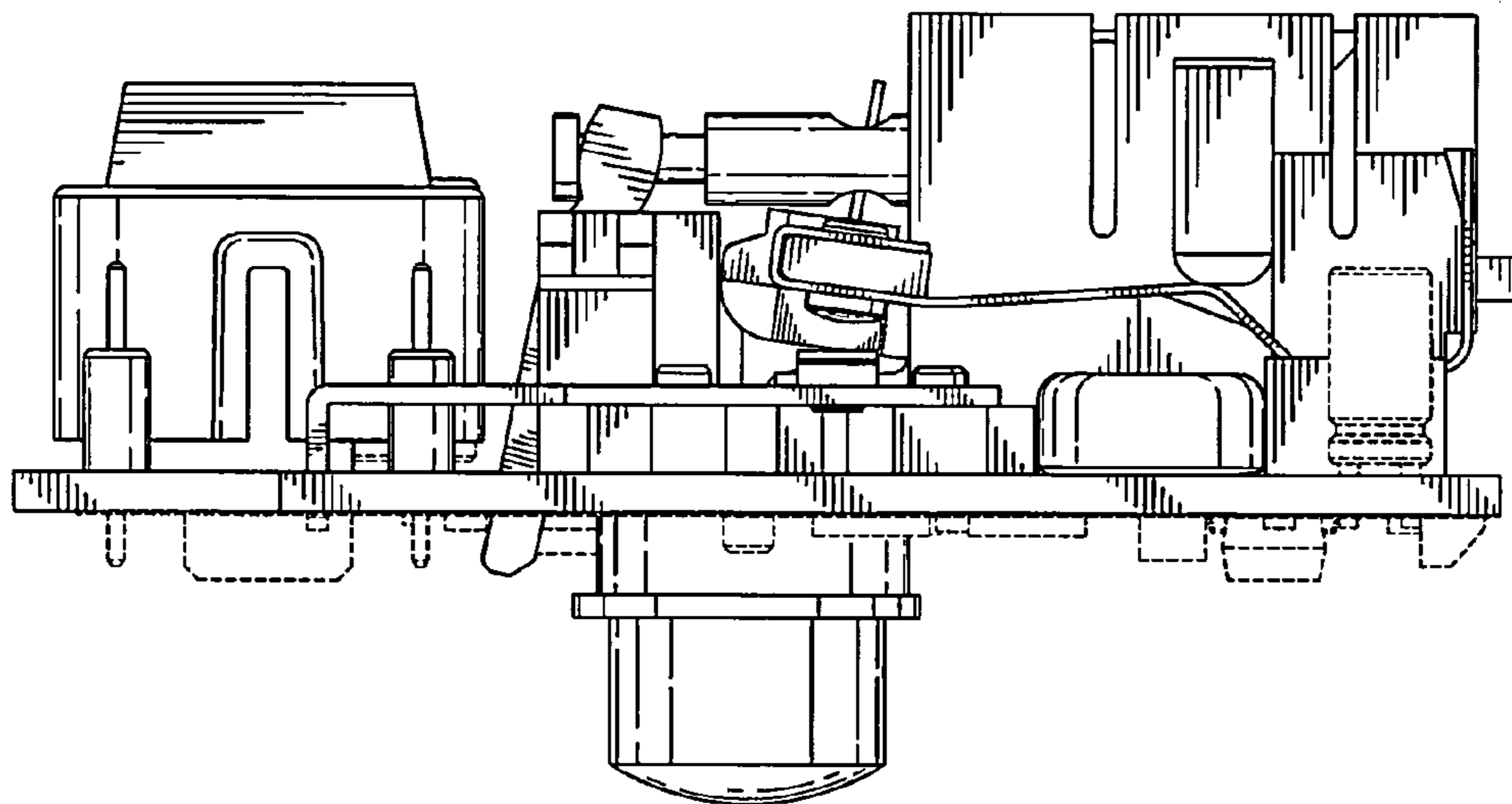


FIG. 6

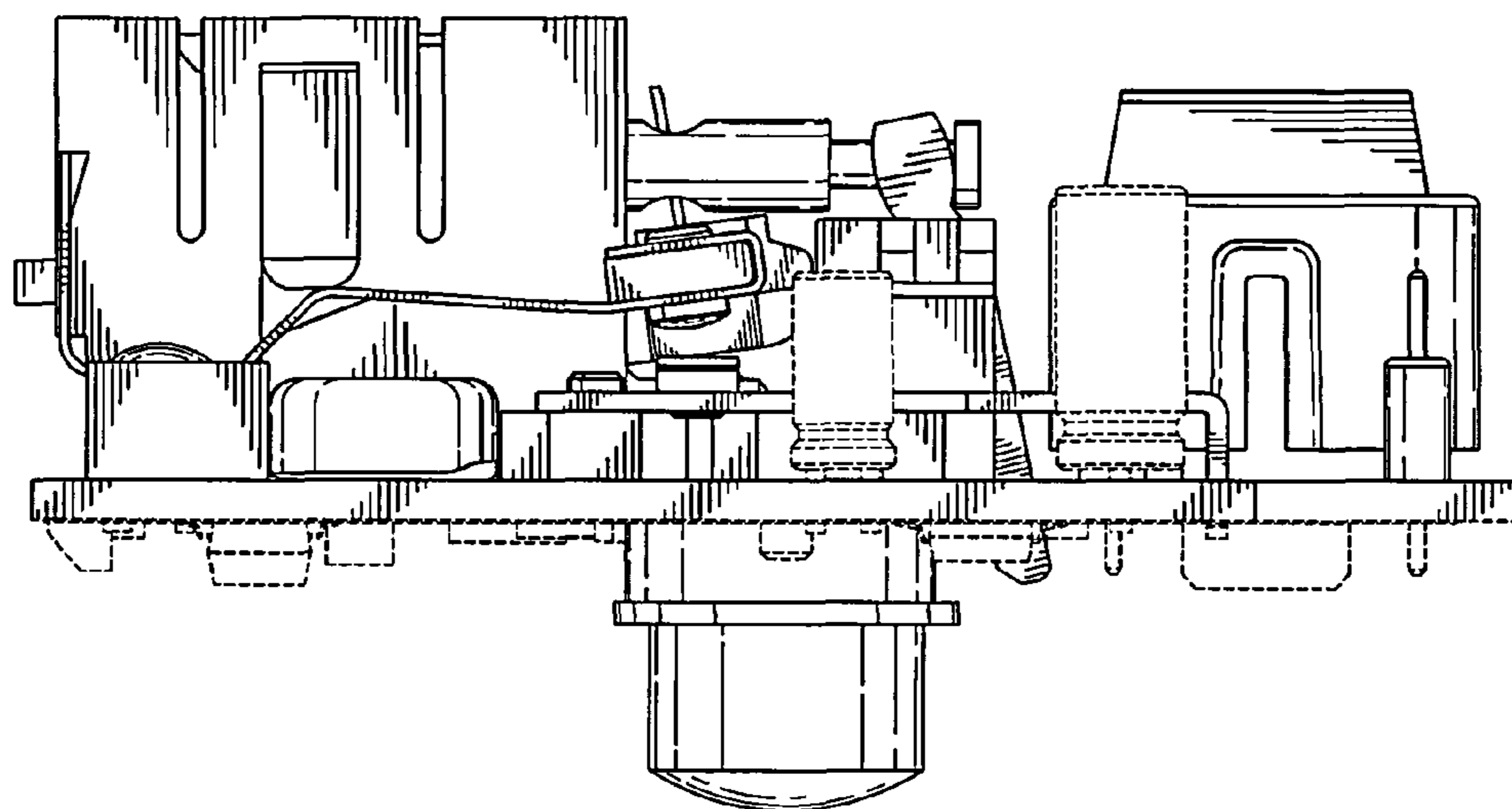


FIG. 7